

Amendments to the CLAIMS:

Without prejudice, this listing of the claims replaces all prior versions and listings of the claims in the present application:

LISTING OF CLAIMS:

1-10. (Canceled).

11. (Currently Amended) A converter module, comprising:

a positive terminal, a negative terminal, a phase terminal, a first semiconductor chip and a second semiconductor chip, the positive terminal, negative terminal, the phase terminal, the first semiconductor chip, and the second semiconductor chip being situated on top of one another in a stack;

wherein at least one of the positive terminal, the negative terminal, and the phase terminal includes a contact plate, a bar-shaped terminal lug which is positioned asymmetrically on the contact plate, and an auxiliary element which prevents the at least one of the positive terminal, the negative terminal, and the phase terminal from tilting about a longitudinal axis of the terminal lug, the auxiliary element being able to be detached after the converter module is assembled;

wherein the phase terminal is structurally arranged identically to one of the positive terminal or the negative terminal.

12. (Canceled).

13. (Previously Presented) The converter module as recited in claim 11, wherein the bar-shaped terminal lug is situated offset with respect to a plane created by the contact plate.

14. (Previously Presented) The converter module as recited in claim 13, wherein at least two of the positive terminal, the negative terminal, and the phase terminal includes a respective bar-shaped terminal lug, each bar-shaped terminal lug being situated offset so that the respective terminal lugs may be brought out from the converter module on a same level.

15. (Previously Presented) The converter module as recited in claim 11, wherein the converter module is situated in an injection molded plastic housing.

16. (Previously Presented) The converter module as recited in claim 11, wherein the auxiliary element has a positioning aperture for positioning the auxiliary element in a joining device.

17. (Currently Amended) A line of multiple single-phase converter modules, comprising:

a plurality of converter modules, each of the converter modules including a positive terminal, a negative terminal, a phase terminal, a first semiconductor chip and a second semiconductor chip, the positive terminal, negative terminal, the phase terminal, the first semiconductor chip, and the second semiconductor chip being situated on top of one another in a stack;

wherein at least one of the positive terminal, the negative terminal, and the phase terminal includes a contact plate, a bar-shaped terminal lug which is positioned asymmetrically on the contact plate, and an auxiliary element which prevents the at least one of the positive terminal, the negative terminal, and the phase terminal from tilting about a longitudinal axis of the terminal lug, the auxiliary element being able to be detached after the converter module is assembled;

wherein the phase terminal is structurally arranged identically to one of the positive terminal or the negative terminal.

18. (Currently Amended) A method for manufacturing a converter module comprising:

providing a positive terminal, a negative terminal, a phase terminal, a first semiconductor chip and a second semiconductor chip, at least one of the positive terminal, the negative terminal, and the phase terminal having a contact plate, a bar-shaped terminal lug, and an auxiliary element, the terminal lug being positioned asymmetrically on the contact plate, the auxiliary element preventing the terminal from tilting about a longitudinal axis of the bar-shaped terminal lug, wherein the phase terminal is structurally arranged identically to one of the positive terminal or the negative terminal;

stacking the positive terminal, the negative terminal, the phase terminal, the first semiconductor chip and the second semiconductor chip on top of one another in a joining device, the phase terminal being situatedly rotated by 180° about the terminal longitudinal axis of the terminal lug in relation to an orientation of one of the structurally identically arranged positive terminal or the structurally identically arranged negative terminal; and encapsulating the stack in an injection molded housing.

19. (Previously Presented) The method as recited in claim 18, wherein at least one of the positive terminal, the negative terminal and the phase terminal is positioned in the joining device using an aperture provided in the auxiliary element.

20. (Previously Presented) The method as recited in claim 18, wherein the positive terminal or the negative terminal and the phase terminal are identical parts which are inserted into the joining device rotated by 180°.